

COMPASS

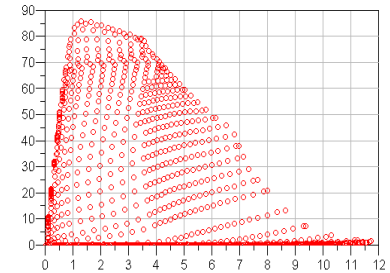
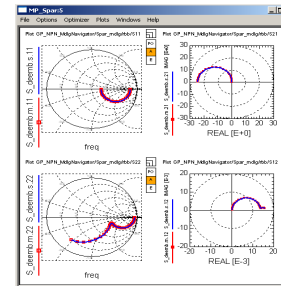
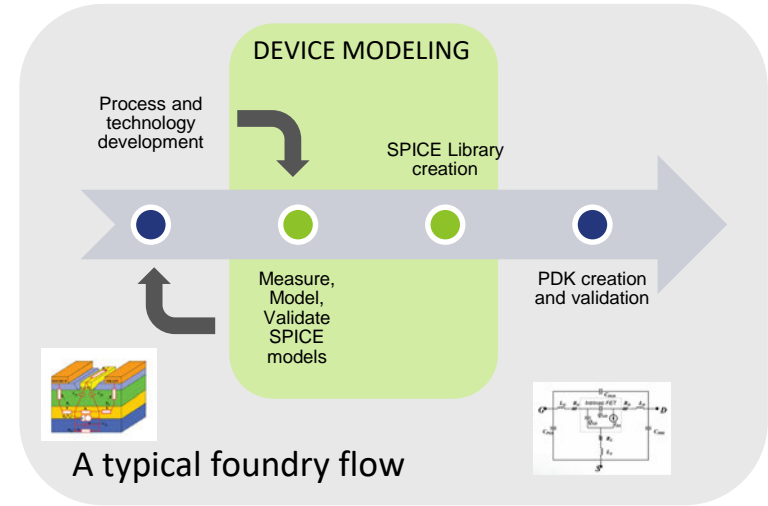
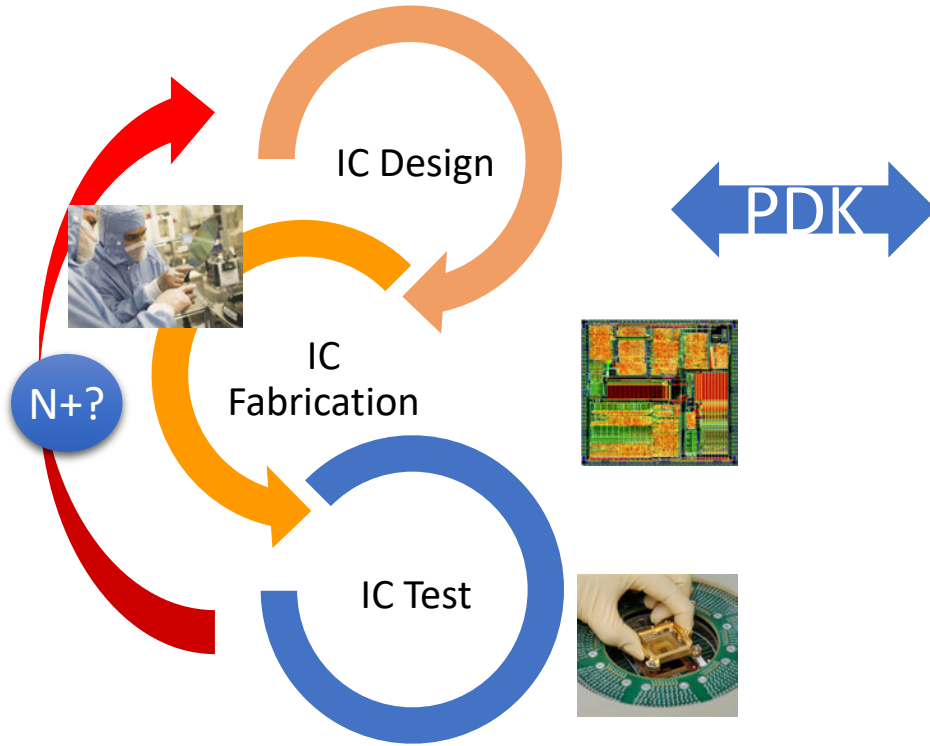
a FormFactor users' group conference



Autonomous RF/mmW Measurement and Calibration to Accelerate 5G Time-to-Data

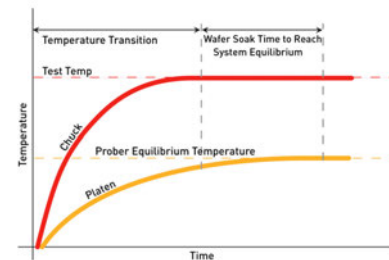
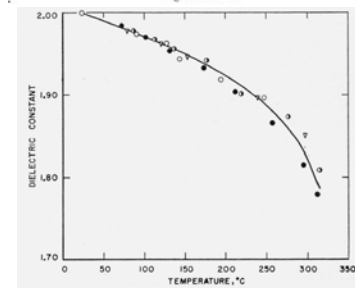
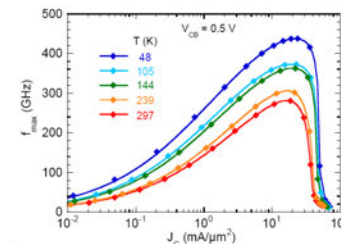
Hank Chiang, Senior Application Engineer
FormFactor

Why is device modeling critical?



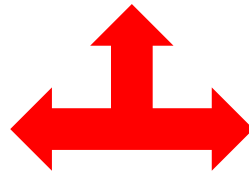
Pain points – testing over temperature

- Measurements at ambient can be challenging, but measuring over temperature is much harder
 - Device modelling for Process Design Kits requires testing from -40degC to +125degC
- Calibration more prone to drift due to expansion of probes and cables
- Probe to pad alignment errors due to expansion of chuck, wafer, platen, positioners, probes and more
- Problems have become more significant with shrinking pad dimensions
 - RF Pads typically as small as 50x50um

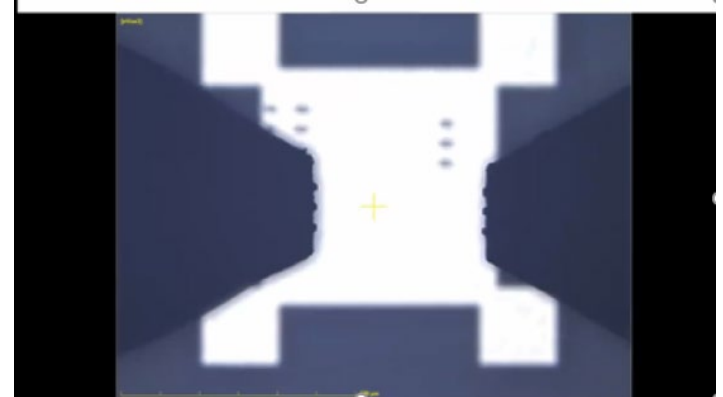


Mechanical effects of growth

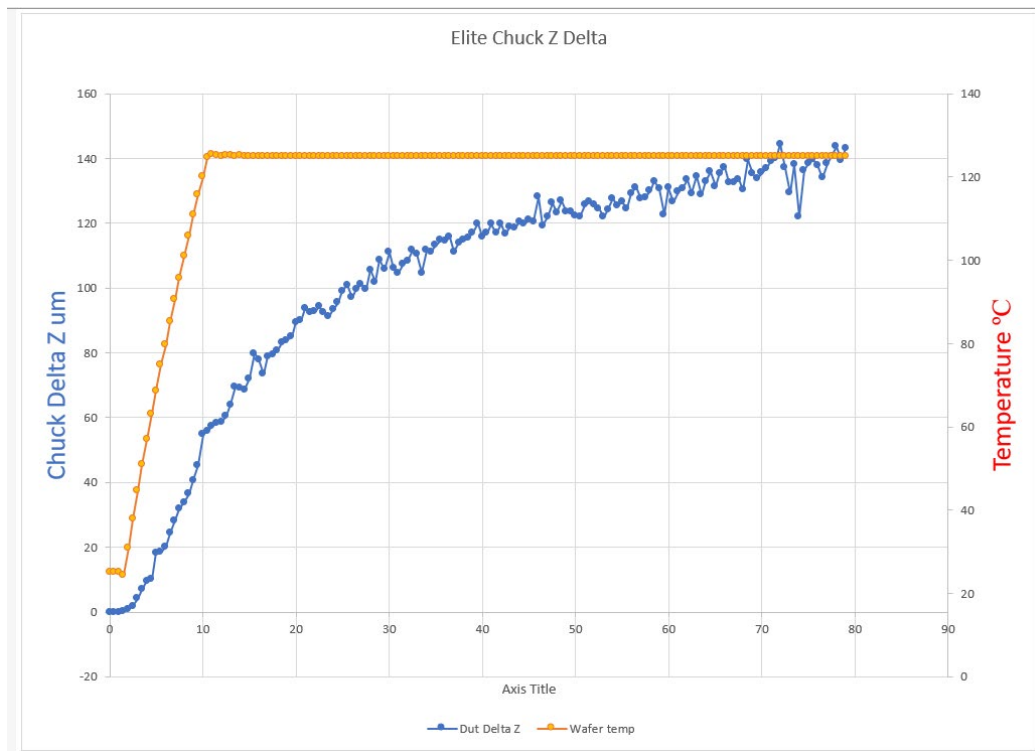
- Probes grow / retract with temperature in XZ
- Some movement in Y but comparatively minimal
- For significant thermal changes evaluate theta also
- Chuck grows in XYZ



25oC>>125C>>25C

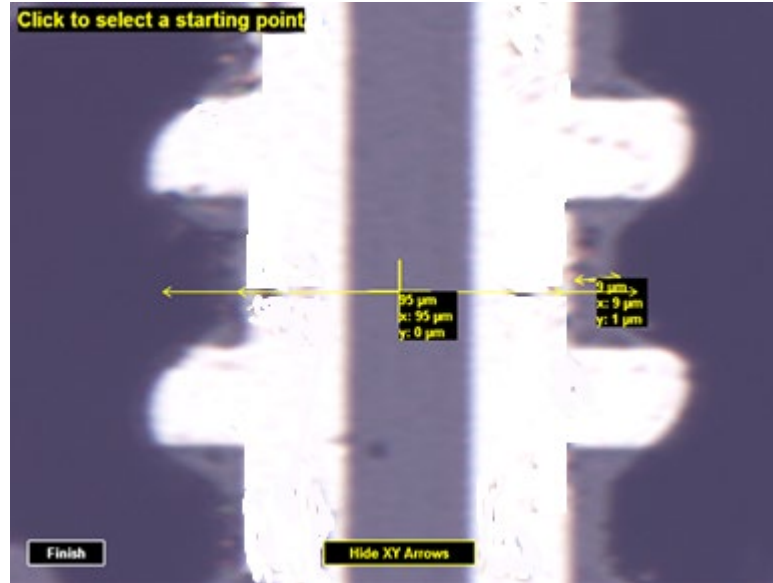
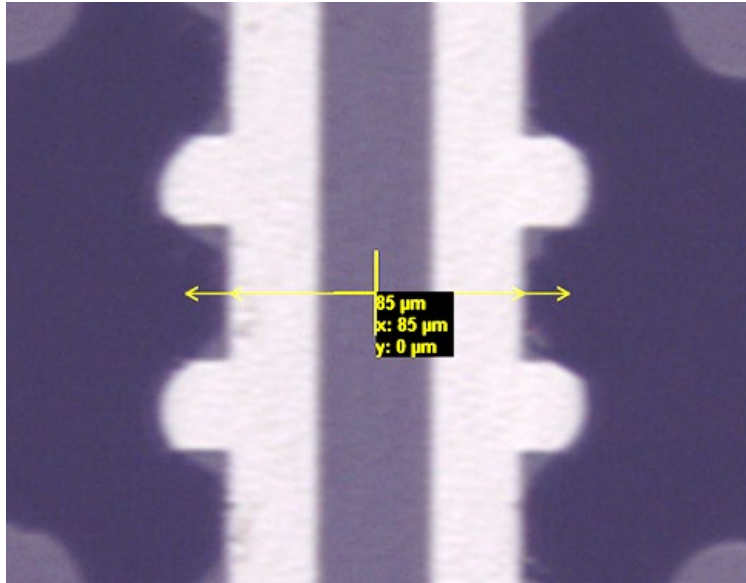


Chuck Z expansion



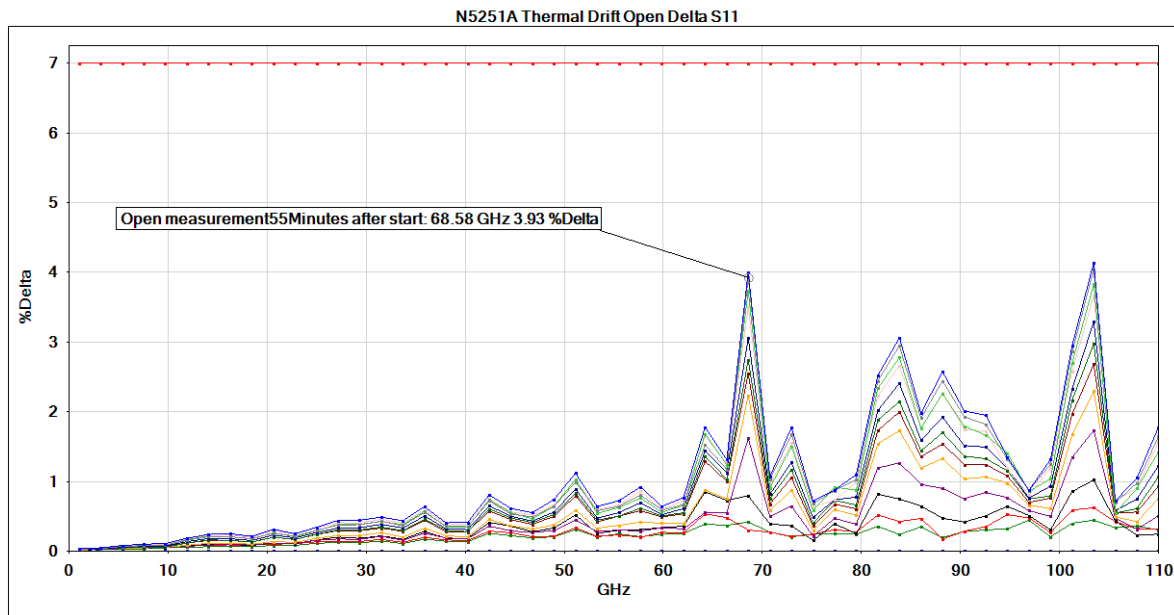
- Chuck to probe geometry change during soak
- Ideally we would like to probe during growth to save time

Mechanical effects during calibration itself



- Probe shrinkage during 1 minute LRRM calibration
- East probe further from hot chuck has 9 μm delta in contact position
- Critical line measurement is measured first in calibration

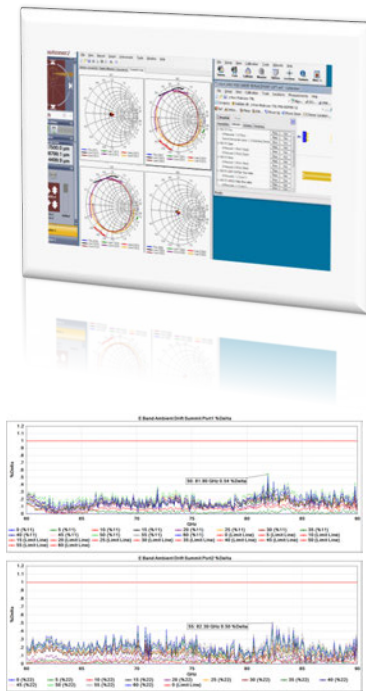
Problem – calibration drift



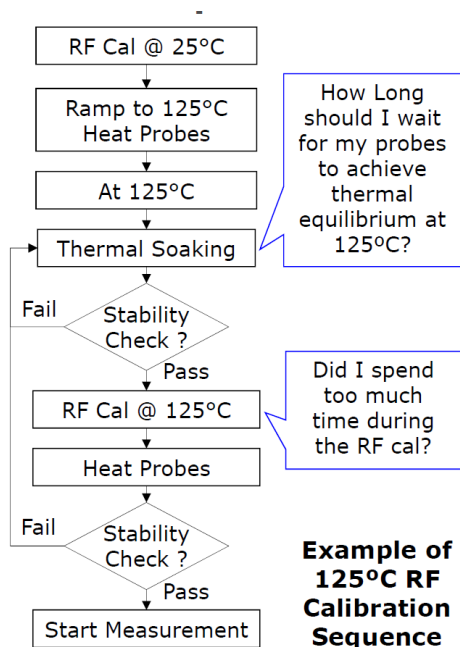
- Calibration drifts with time and temperature changes
- Magnitude increases with frequency
- Transitioning chuck temperature invalidates calibration
- Drift has been greatly improved using N5291A system but still a consideration

Pain points – calibration drift

- Even a good calibration will drift with time, temperature changes and movement of cables
 - Even small temperature changes in the room, can cause higher frequency calibrations to drift
- There is no automation of monitoring the magnitude of drift error
 - Manual checks can be made of the open standard at any time, but automating this requires programming in the test executive
- And no autonomous way to re-calibrate once the drift has exceeded a limit
 - If the calibration is found to be no longer valid, then the user needs to stop the testing and perform the whole calibration again



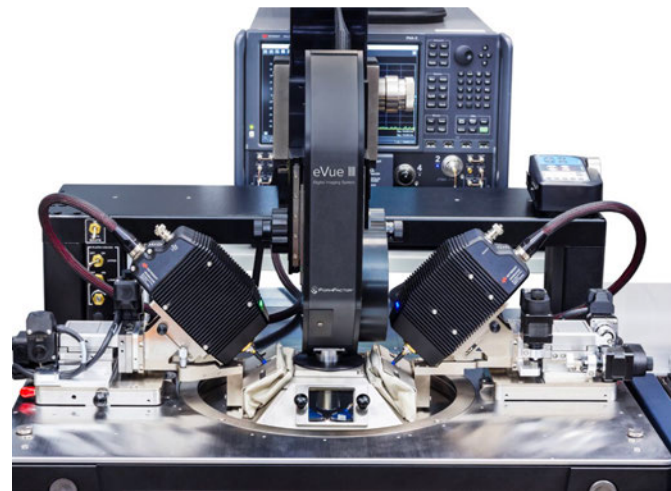
Over temperature calibration general approach



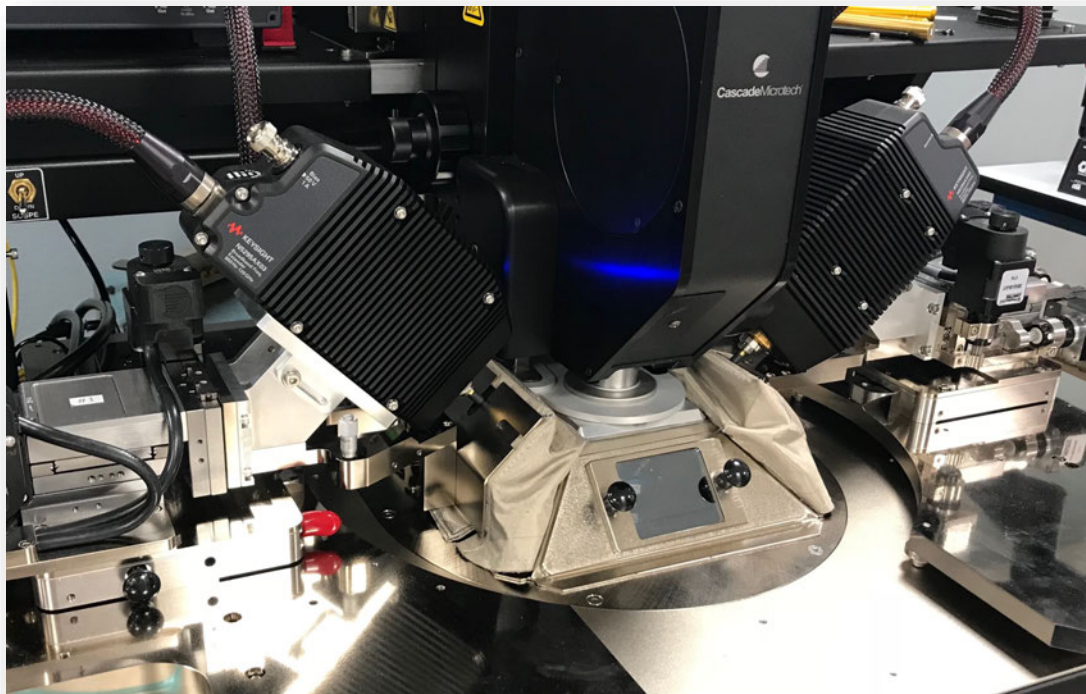
- Doing all of this takes skill patience and experience
- Doing things without the checks can result in erroneous data
- Getting calibration fast enough is very tricky even for experienced users and compromises are often made
- Machine must be “nursed”

Introducing – Autonomous RF Measurement Assistant

- True Automatic, hands free calibration
- Setup of Calibration requires no expert placement, all automatic
- Monitors calibration drift, re-calibrates automatically
- Full management of system expansion and RF stability
- Full thermal automatic calibration
- Save time & increase data accuracy
- Corrects “thermally induced” probe electrical errors



Reduced path length and improved performance



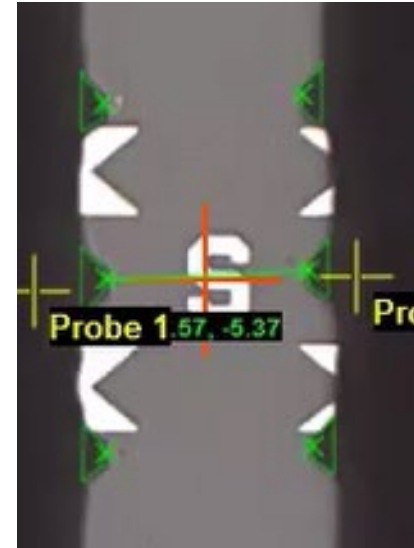
- Compact high resolution programmable positioner
- Tophat designed to minimise cable lengths and prevent stiction which impacts motorised positioner accuracy
- Reducing cable length helps to improve system drift and dynamic range
- Autonomous RF currently limited to max 130 GHz and Infinity probes

Integrating automation assistant into test executive



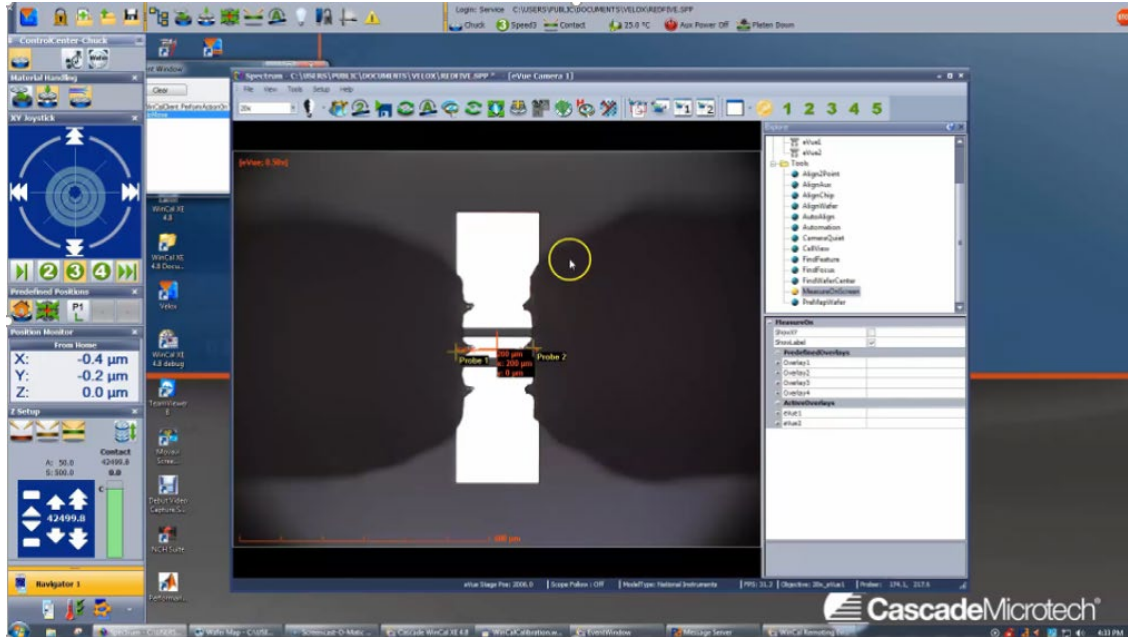
- Yellow Coloured processes are the two new commands StartAutomationTemperature GetAutomationTemperature Status
- Test exec never needs to ask system to calibrate, monitor or soak. Its all automatic
- Only needs to send temperature automation, wait till complete and then step to numbered die as normal
- Next die commands will check for drift, recalibrate if needed and automate probe on die placement
- supports different probe spacings for automatic movement to different device topologies

Training Autonomous RF – tip finding



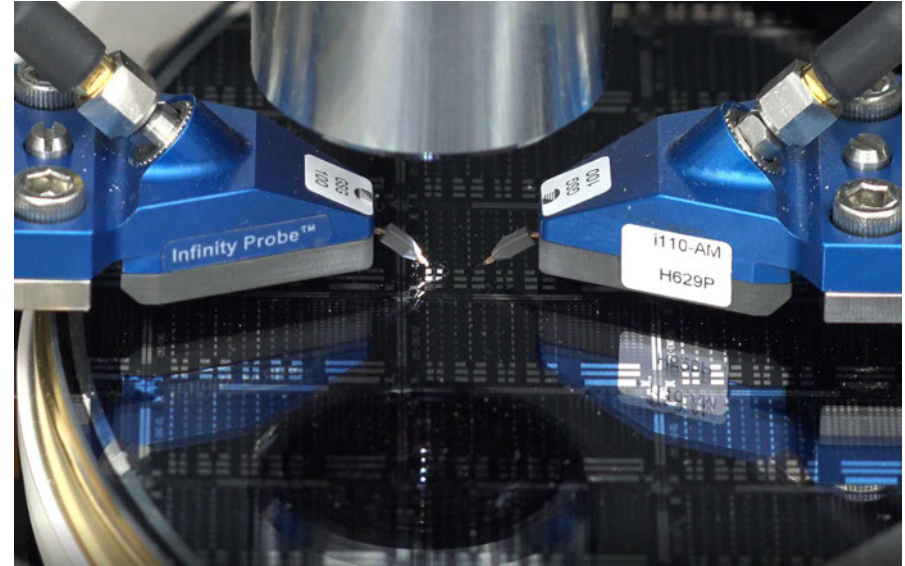
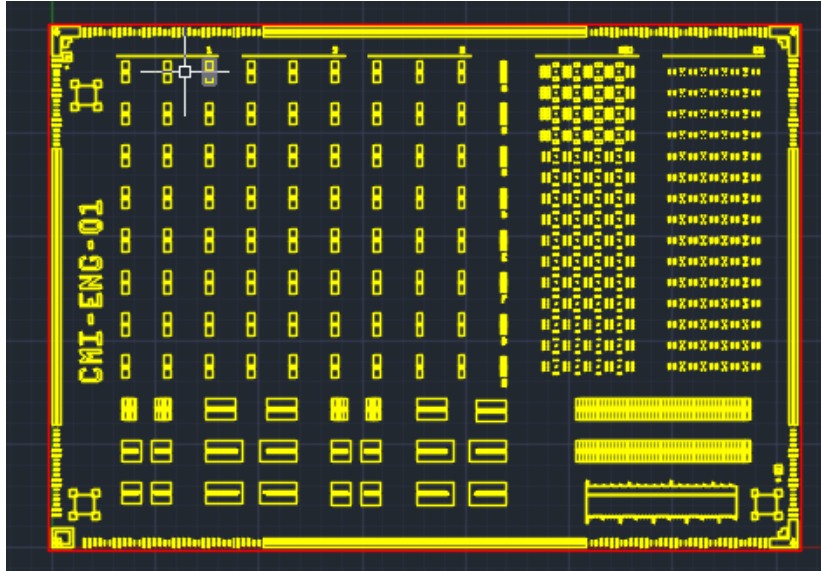
- Auto RF tip location and iteration is at the heart of the process
- Required for Autonomous calibration

Autonomous RF measurement setup video



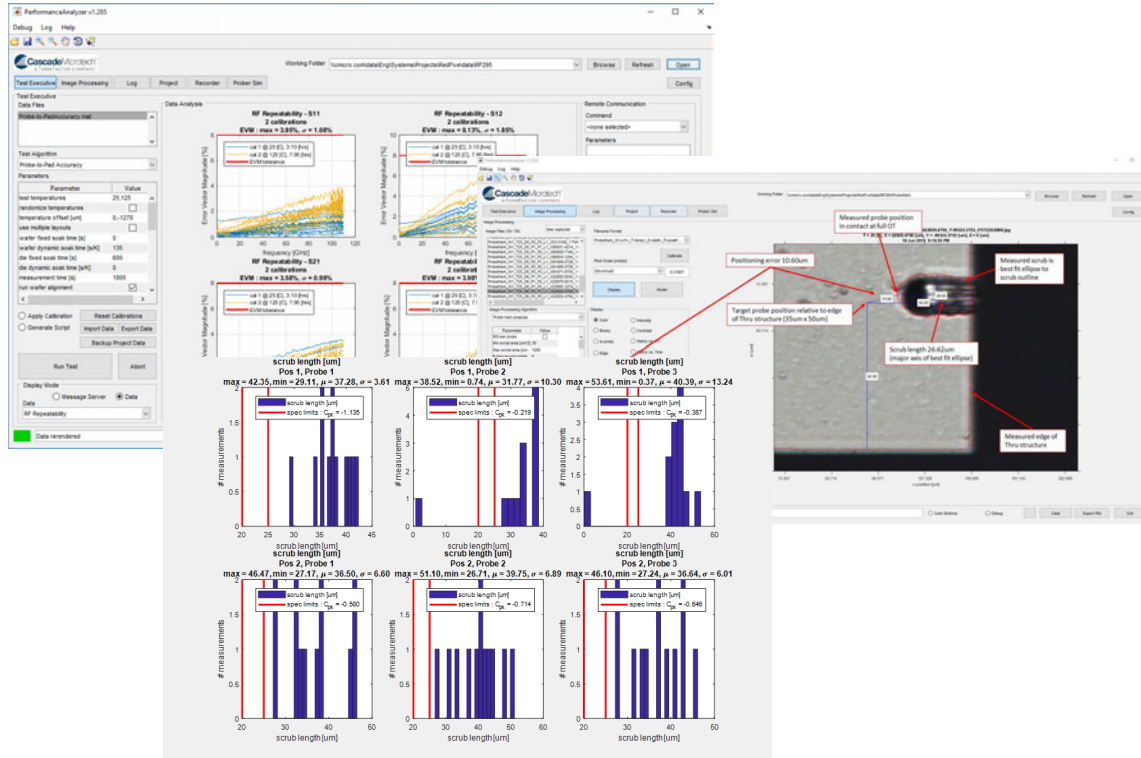
[Video](#)

Custom validation wafer for performance evaluation



- Aluminium on glass Wafer contains array of validation lines and offset shorts and other open structures
- 200 and 300 mm versions
- Used for factory and field performance evaluation

Performance analyser



- FormFactor internal reference tool used to benchmark automation performance automatically
- Gives measurement deltas of standard across the wafer
- Statistical measurements are given from optical mark inspection to evaluate positioning error

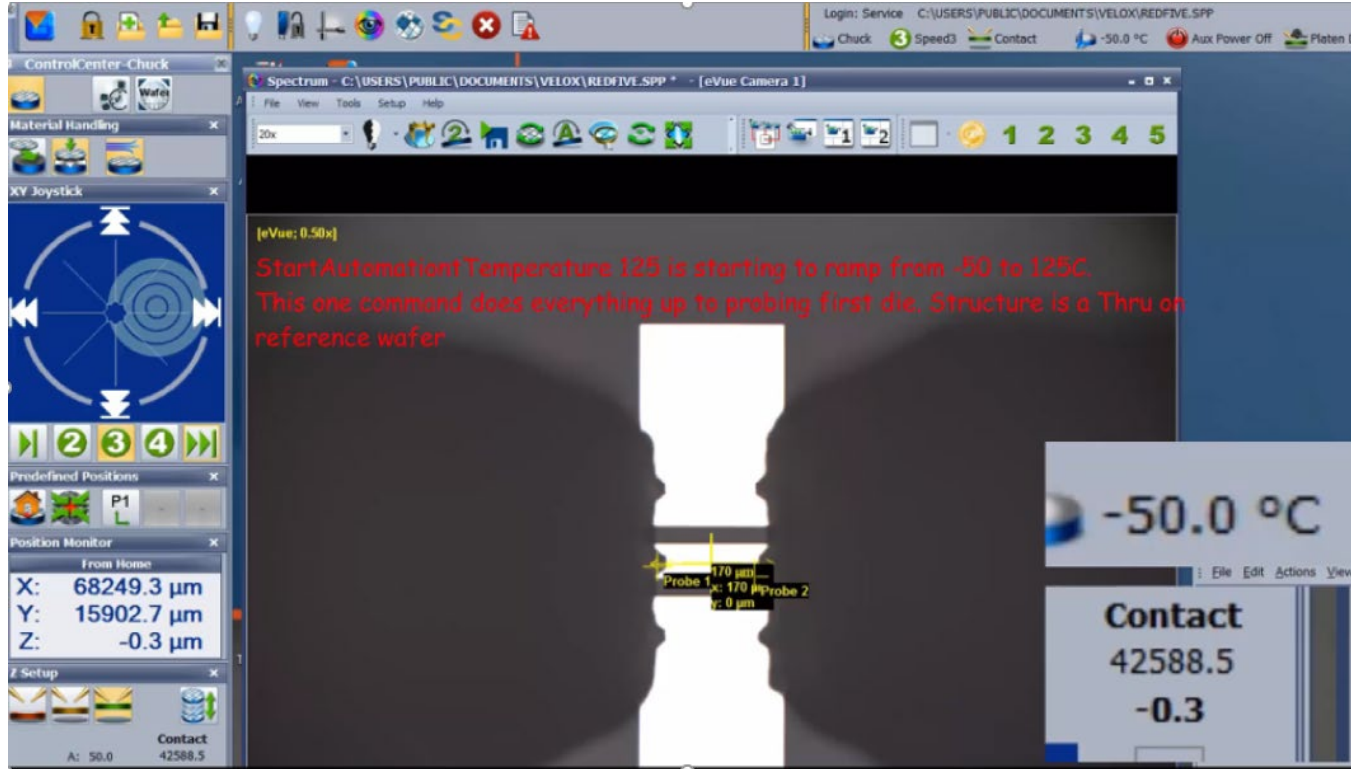
Autonomous RF Key Value Propositions

- **Ease of use** – An inexperienced operator can perform an RF calibration up to 130 GHz by simply pushing a button. This reduces the need of the experienced users full time on each system
- **Reduced Soak Time** – System will re-align the probes to the pads if they drift away from alignment. This reduces the time of test and increases throughput
- **Unattended Use** – Measurements can be left running over night, testing all devices on the wafer, and at different temperatures without the need of the operator.
- **Calibration Monitor and Re-calibration** – System will continuously monitor calibration drift, and automatically re-calibrate the system should the drift exceed a pre-defined limit
- **Data volume** – unattended test allows more tool utilisation without additional time and money

Faster Time to Data

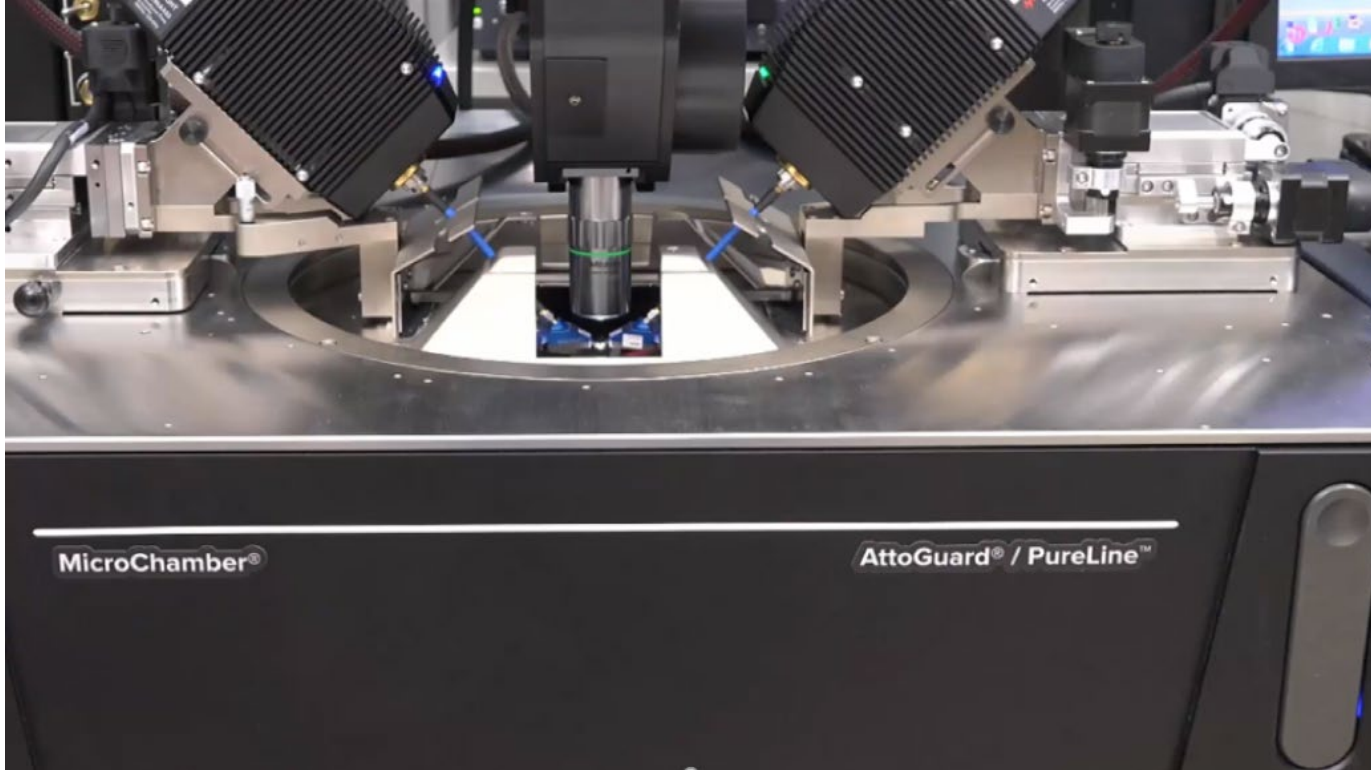
Lower Cost of Testing

Video – temperature transition run -50C to 125C



[Video](#)

Video – SUMMIT200



[Video](#)